

# Claims

- [c1] 1.A multiple-milling process for manufacturing printed circuits, constituted by a process for preparing the substrate of printed circuit boards (1) for the production of bending areas (2) from whence to bend such printed circuits (1), characterized by consisting of performing the undercutting in multiple parallel strips on the printed circuit's support substrate by means of a milling tool (3) allowing for the subsequent bending of the printed circuit up to a value of  $180^{\circ}$  without deteriorating the metallic material conductive tracks adhered to the printed circuit substrate on the side opposite the milled surface.
- [c2] 2.A multiple-milling process for manufacturing printed circuits according to claim 1, characterized in that the milling tool is a mill comprising a roll provided with multiple polishing strips or teeth on its surface.
- [c3] 3.A printed circuit obtained according to the process disclosed in claims 1 and 2, characterized in that the conductive layer's thickness ranges between 65 and 400 microns.

- [c4] 4.A printed circuit obtained according to the process disclosed in claims 1 and 2, characterized in that the thickness conductive layer is 105 microns.
- [c5] 5.A printed circuit obtained according to the process disclosed in claims 1 and 2, characterized in that the conductive layer's material is copper.